

## P-Ch 20V Fast Switching MOSFETs

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

## Product Summary



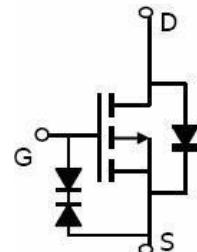
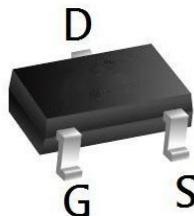
BVDSS	RDS(on)	ID
-20V	29mΩ	-5.0A

## Description

The XR3415E is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The XR3415E meet the RoHS and Green Product requirement with full function reliability approved. ESD Rating: 2500V HBM

## SOT23 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
V <sub>DS</sub>	Drain-Source Voltage		-20	V
V <sub>GS</sub>	Gate-Source Voltage		±10	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	-5.	-4.	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	-4.	-3.7	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>		-18	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1.32	1	W
T <sub>STG</sub>	Storage Temperature Range		-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range		-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	125	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤ 10s)	---	95	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	80	°C/W

## P-Ch 20V Fast Switching MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise specified)

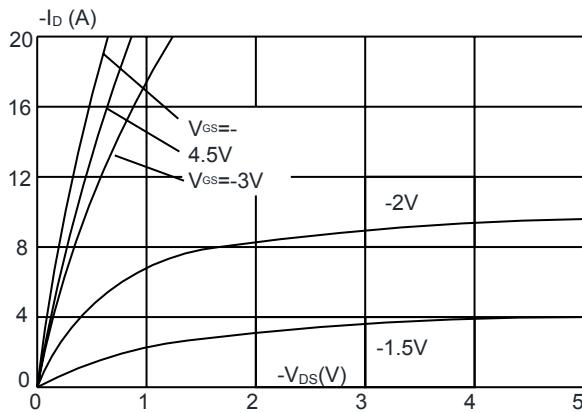
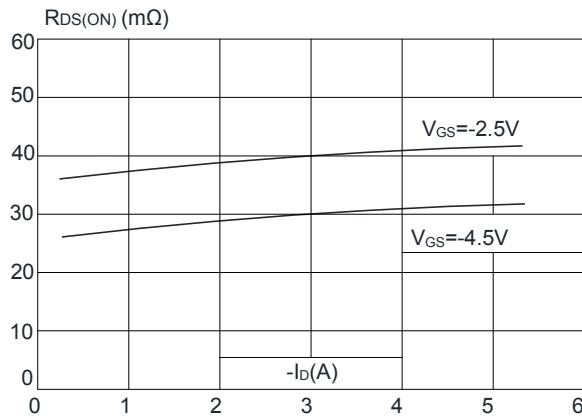
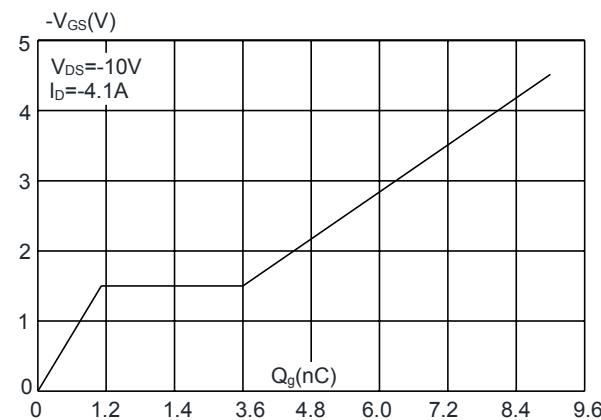
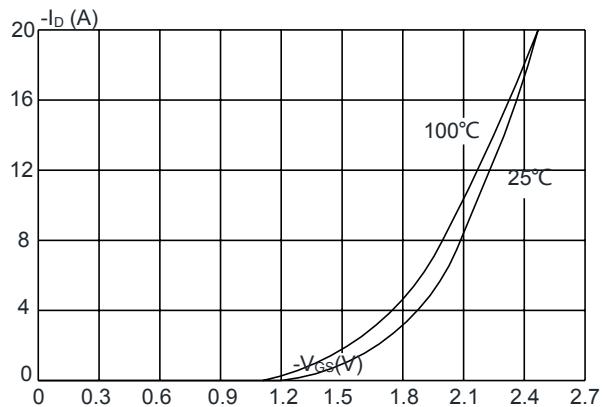
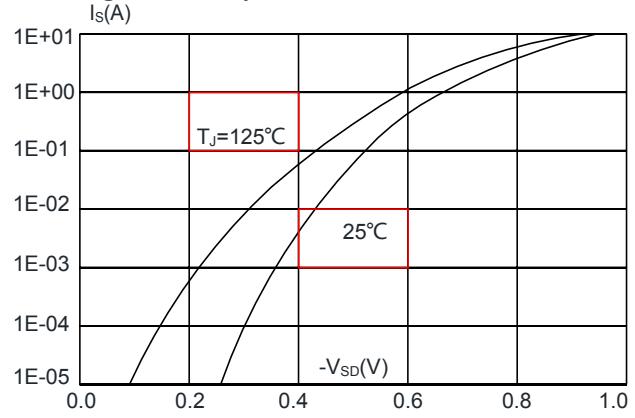
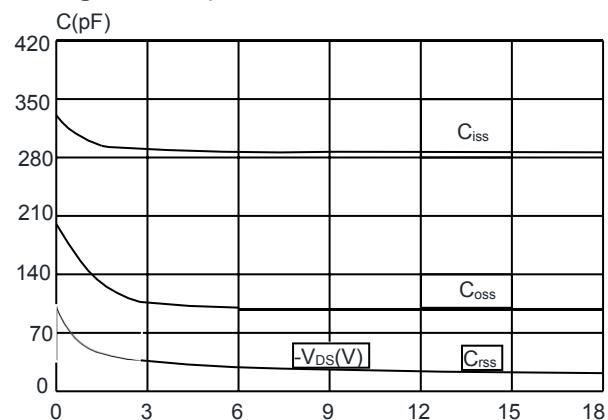
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D = -250\mu\text{A}$	-20	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}$ ,	-	-	-1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 10\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.4	-0.7	-1.0	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS} = -4.5\text{V}, I_D = -4\text{A}$	-	29	40	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}, I_D = -3\text{A}$	-	40	56	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	-	289	-	pF
$C_{oss}$	Output Capacitance		-	98	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	22	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = -10\text{V}, I_D = -4.1\text{A}, V_{GS} = -4.5\text{V}$	-	9	-	nC
$Q_{gs}$	Gate-Source Charge		-	1	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	2.6	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -10\text{V}, R_G = 1\Omega, V_{GEN} = -4.5\text{V}, R_L = 1.2\Omega$	-	12	-	ns
$t_r$	Turn-on Rise Time		-	35	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	30	-	ns
$t_f$	Turn-off Fall Time		-	10	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	-4.1	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-16.4	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = -4.1\text{A}$	-	-	-1.2	V

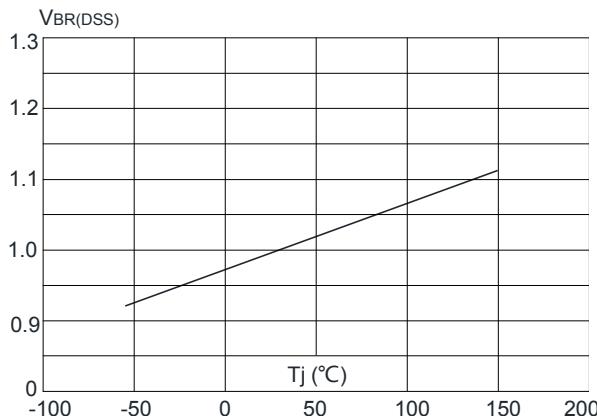
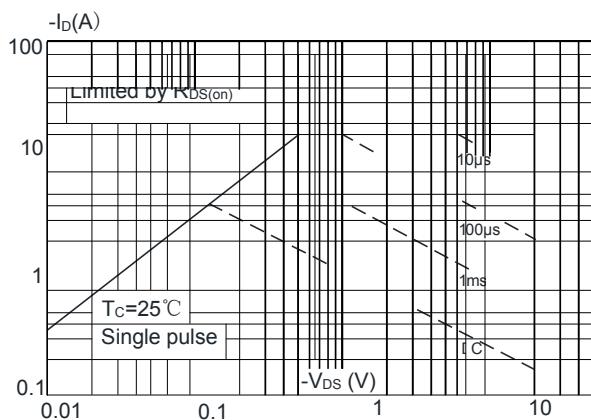
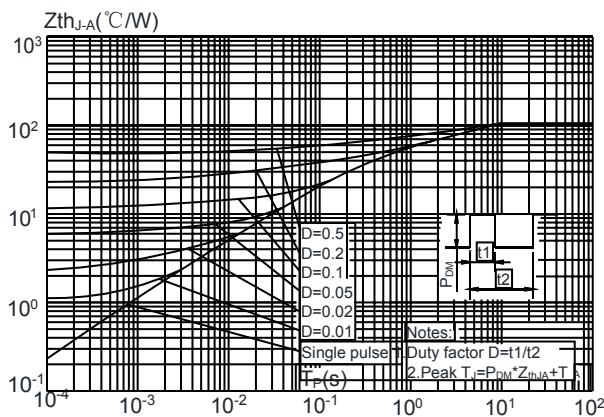
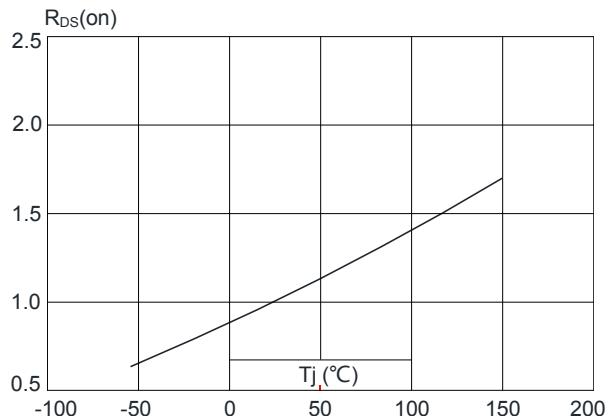
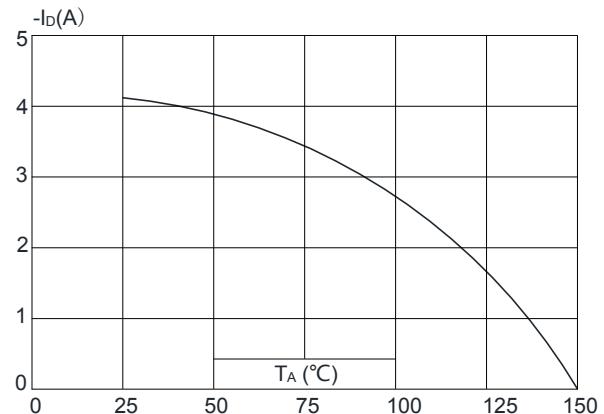
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

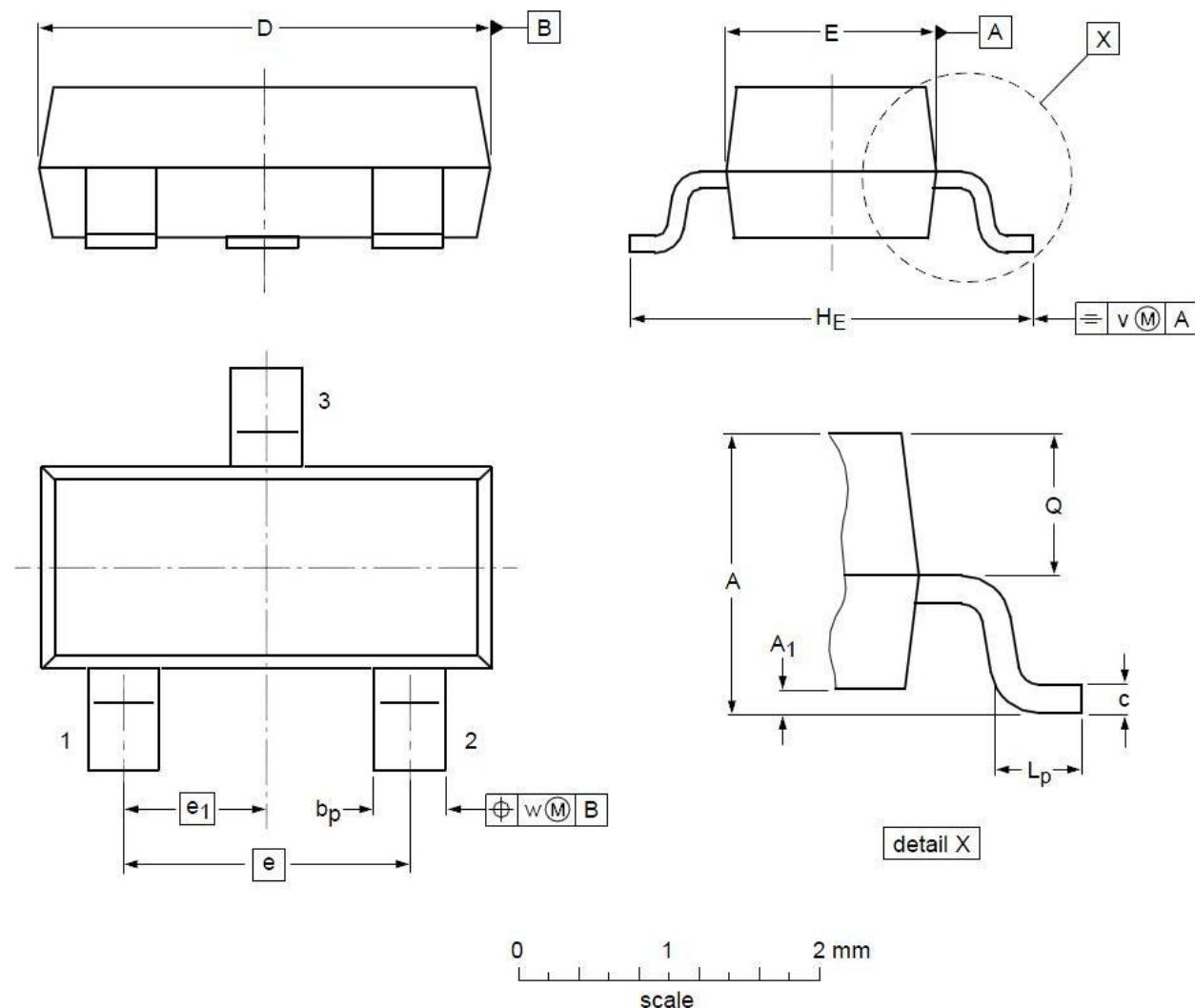
## P-Ch 20V Fast Switching MOSFETs

## Typical Performance Characteristics

**Figure 1:** Output Characteristics**Figure 3:** On-resistance vs. Drain Current**Figure 5: Gate Charge Characteristics****Figure 2:** Typical Transfer Characteristics**Figure 4:** Body Diode Characteristics**Figure 6: Capacitance Characteristics**

**P-Ch 20V Fast Switching MOSFETs****Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature**Figure 9:** Maximum Safe Operating Area**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**Figure 8:** Normalized on Resistance vs. Junction Temperature**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature

## SOT23 Mechanical Data



## DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.01	1.15	A <sub>1</sub>	0.01	0.05	0.10
b <sub>p</sub>	0.30	0.42	0.50	c	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e <sub>1</sub>	--	0.95	--
H <sub>E</sub>	2.25	2.40	2.55	L <sub>p</sub>	0.30	0.42	0.50
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				